

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
BYOUNG HAK KIM	06/12/2019
SEUNG WOO BAIK	06/12/2019
JUNE BEOM CHOI	06/12/2019
IN WOONG KIM	06/12/2019
JONG YEOL JUNG	06/12/2019
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16457152
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ATTORNEY DOCKET NUMBER:	583ZEUS0001US
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SIGNATURE:	/Shin-Chih Hu/
DATE SIGNED:	07/01/2019
Total Attachments: 2 source=41E3629#page1.tif	

ASSIGNMENT OF PATENT APPLICATION

WHEREAS, the below named individual(s), hereinafter referred to as "Assignors," are the inventor(s) of the invention described and set forth in the below-identified application for United States Letters Patent;

Title of Invention: CONDUCTIVE POROUS CERAMIC
SUBSTRATE AND METHOD OF
MANUFACTURING SAME

Filing Date: June 28, 2019

Application No.: 16/457,152

Attorney Docket No.: 583ZEUS0001US

WHEREAS, **MAX TECH CO., LTD.**, located at 19, Seongseoseo-ro 47-gil, Dalseo-gu, Daegu, 42702 Republic of Korea, hereinafter referred to as "ASSIGNEE," is desirous of acquiring ASSIGNORS' interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;


NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have sold, assigned and transferred, and by these presents do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all their right, title and interest in and to the said invention and application including any corresponding foreign application, and in and to any Letters Patent which may hereafter be granted on the same in the United States and any corresponding foreign application, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignors had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in Assignee, or Assignee's successors and assigns.

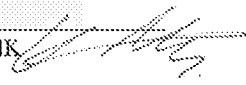
Assignors hereby authorize and request AMPACC Law Group, PLLC, 6100 219th Street SW, Suite 580, Mountlake Terrace, WA 98043, to insert herein above the title, application number, and filing date of said application when known.

IN TESTIMONY WHEREOF, each below named inventor, collectively Assignors,
has signed on the dates indicated.


Date: 2019.6.12

Inventor's Name: Byoung Hak KIM 

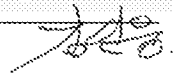
Date: 2019.6.12

Inventor's Name: Seung Woo BAIK 

Date: 2019.6.12

Inventor's Name: June Beom CHOI 

Date: 2019.6.12

Inventor's Name: In Woong KIM 

Date: 2019.06.12

Inventor's Name: Jong Yeol JUNG 